

PLATING APPARATUS AND CONTAINER BATH

ABSTRACT

Provided are a plating apparatus and a container bath, which have a simpler structure than a
5 conventional system and are capable of improving uniformity of a plating thickness. The
plating apparatus (M) includes a plating tank (10) which stores a plating liquid (F), a cathode
member (20) arranged inside the plating tank (10), a plating object (W) arranged inside the
plating tank (10) to face the cathode member (20), an anode jig (30) which contacts with the
plating tank (10) to face the cathode member (20), an anode jig (30) which contacts with the
10 plating object (W), and a space (40) formed between the cathode member (20) and the plating
object (W) to be a flow passage to which the plating liquid (F) flows from the plating tank (10).
The plating liquid (F) flows into the space (40) from above relative to the space (40), and is
sucked by a pump (50) from below relative to the space (40).

Figure 1

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